

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

Stefan Hau-Riege et al.

Serial No.: Not yet assigned

Filed: Herewith

For: WAFER-BONDING USING SOLDER  
AND METHOD OF MAKING THE SAME

Which is a Divisional of Application of:

Serial No: 10/015,618

Filed: December 17, 2001

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

) Examiner: Not yet assigned

) Art Unit: Not yet assigned

**PRELIMINARY AMENDMENT**

Sir:

Applicants respectfully request that this Preliminary Amendment be entered prior to examination of the above-identified patent application.

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Date of Deposit: September 25, 2003

I hereby certify that I am causing this paper or fee to be deposited with the United States Postal Service "Express Mail Post Office to Addressee" service on the date indicated above and that this paper or fee has been addressed to Mail Stop New Patent Application, COMMISSIONER FOR PATENTS, P.O. Box 1450, Alexandria, VA 22313-1450

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September 25, 2003

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